



ALPHA & OMEGA
SEMICONDUCTOR

AO3400A

N-Channel Enhancement Mode Field Effect Transistor



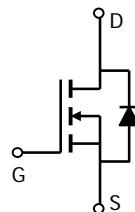
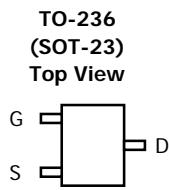
General Description

The AO3400A uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications. Standard Product AO3400A is Pb-free (meets ROHS & Sony 259 specifications).

Features

$V_{DS} (V) = 30V$
 $I_D = 5.7A (V_{GS} = 10V)$
 $R_{DS(ON)} < 26.5m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 32m\Omega (V_{GS} = 4.5V)$
 $R_{DS(ON)} < 48m\Omega (V_{GS} = 2.5V)$

Rg, Ciss, Coss, Crss Tested



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^{AF}	I_D	5.7	A
$T_A=70^\circ C$		4.7	
Pulsed Drain Current ^B	I_{DM}	25	A
Power Dissipation	P_D	1.4	W
$T_A=70^\circ C$		0.9	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	$^\circ C/W$
Maximum Junction-to-Ambient ^A		100	125	$^\circ C/W$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	63	80	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=125^\circ\text{C}$			1 5	uA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.7	1	1.5	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	25			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=5.7\text{A}$		22	26.5	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		31	38	
		$V_{GS}=4.5\text{V}, I_D=5\text{A}$		25.4	32	
		$V_{GS}=2.5\text{V}, I_D=3\text{A}$		34	48	
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=5.7\text{A}$		26		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.72	1.0	V
I_s	Maximum Body-Diode Continuous Current				2.0	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		900	1100	pF
C_{oss}	Output Capacitance			88		pF
C_{rss}	Reverse Transfer Capacitance			65		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		0.95	1.5	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=15\text{V}, I_D=5.7\text{A}$		10	13	nC
Q_{gs}	Gate Source Charge			1.8		nC
Q_{gd}	Gate Drain Charge			3.75		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=2.6\Omega, R_{\text{GEN}}=3\Omega$		3.2		ns
t_r	Turn-On Rise Time			3.5		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			21.5		ns
t_f	Turn-Off Fall Time			2.7		ns
t_{rr}	Body Diode Reverse Recovery Time	$IF=5.7\text{A}, dI/dt=100\text{A/us}$		16.8	20	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$IF=5.7\text{A}, dI/dt=100\text{A/us}$		8		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using <300 us pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

F: The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

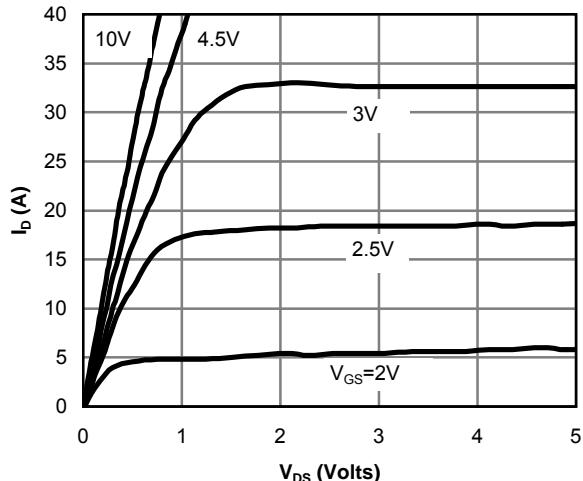


Figure 1: On-Region Characteristics

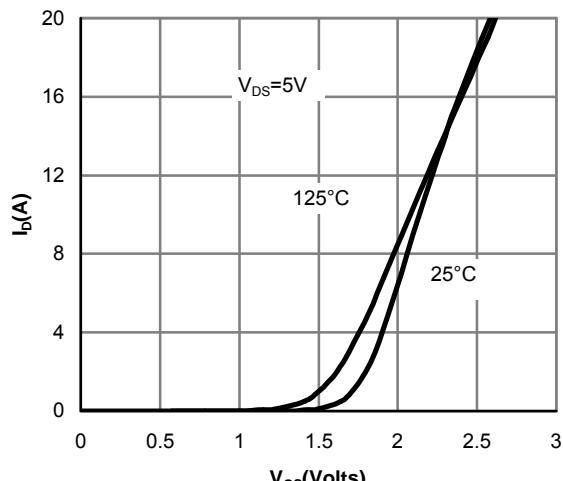


Figure 2: Transfer Characteristics

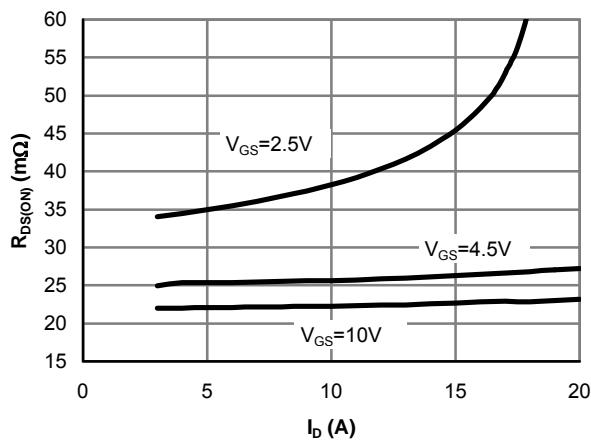


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

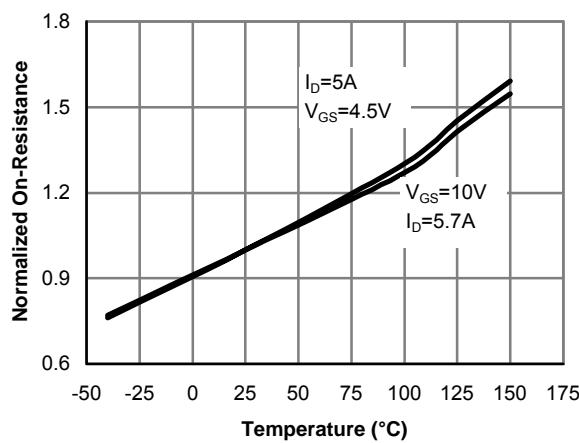


Figure 4: On-Resistance vs. Junction Temperature

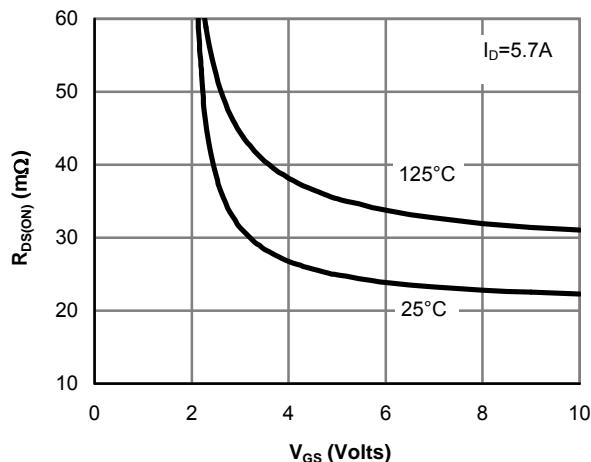


Figure 5: On-Resistance vs. Gate-Source Voltage

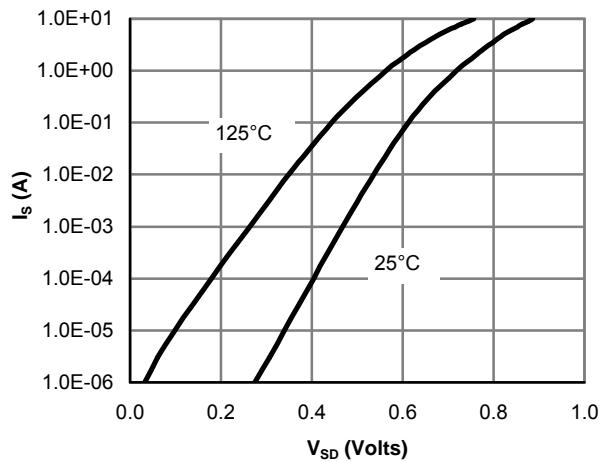


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

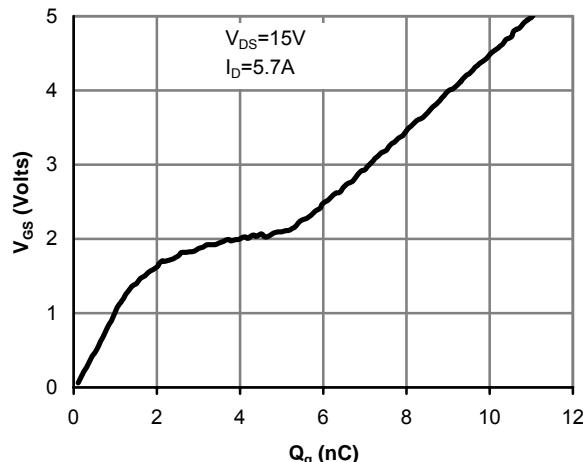


Figure 7: Gate-Charge Characteristics

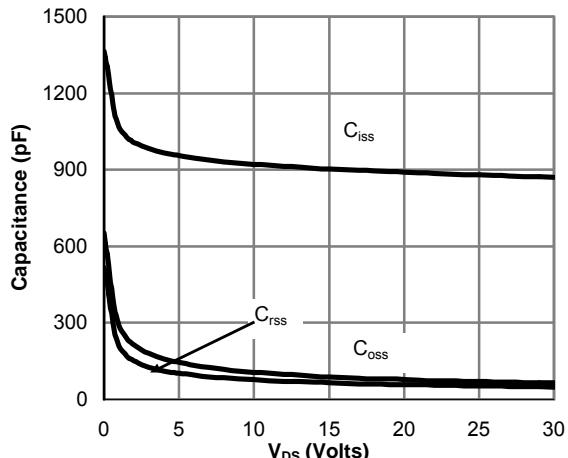


Figure 8: Capacitance Characteristics

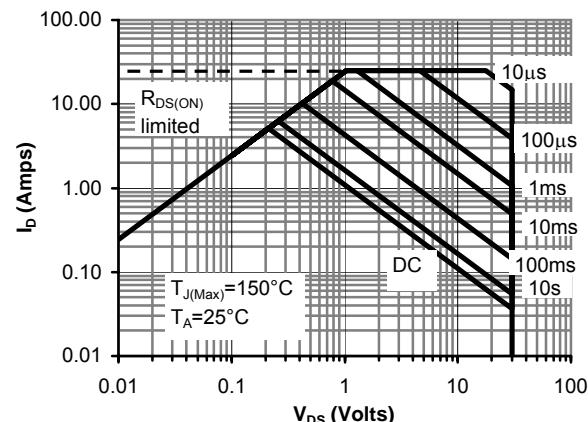


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

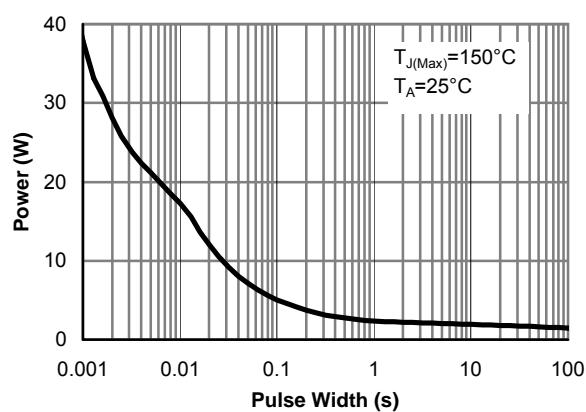


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

